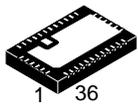


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

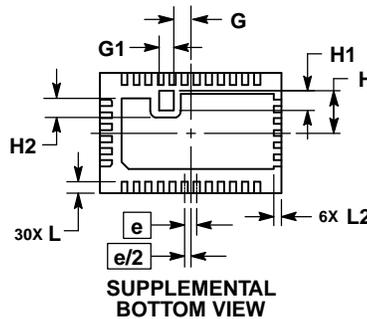
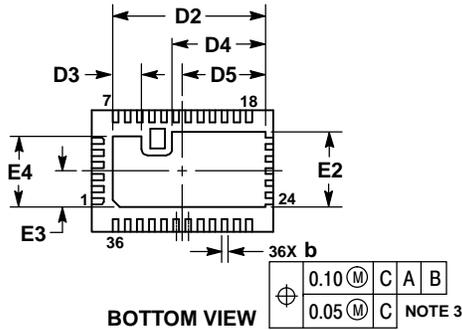
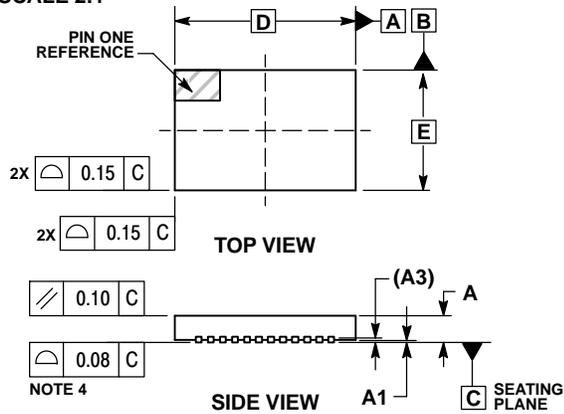
ON Semiconductor®



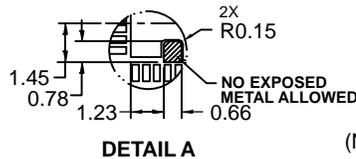
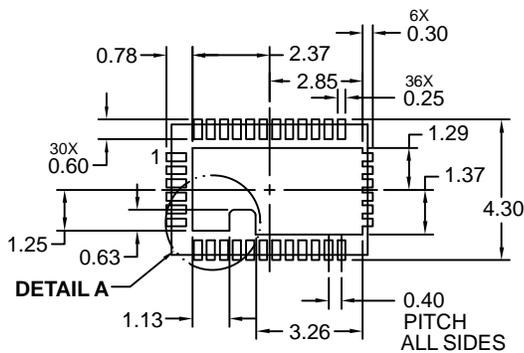
SCALE 2:1

QFN36 6x4, 0.4P
CASE 485DZ
ISSUE A

DATE 19 JUN 2015



RECOMMENDED SOLDERING FOOTPRINT*

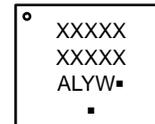


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS | | |
|-------------|------|------|
| DIM | MIN | MAX |
| A | 0.90 | 1.20 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 | REF |
| b | 0.15 | 0.25 |
| D | 6.00 | BSC |
| D2 | 4.95 | 5.05 |
| D3 | 0.91 | 1.01 |
| D4 | 3.04 | 3.14 |
| D5 | 2.70 | 2.80 |
| E | 4.00 | BSC |
| E2 | 2.44 | 2.54 |
| E3 | 1.14 | 1.24 |
| E4 | 2.29 | 2.39 |
| e | 0.40 | BSC |
| G | 0.52 | 0.62 |
| G1 | 0.43 | 0.53 |
| H | 1.35 | 1.45 |
| H1 | 0.60 | 0.70 |
| H2 | 0.57 | 0.68 |
| L | 0.30 | 0.50 |
| L2 | 0.15 | 0.35 |

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|----------------------------------|--|
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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | QFN36 6X4, 0.4P | PAGE 1 OF 2 |

